

ABSTRACT

A laser processing device configured to form an irradiation point of a laser beam for processing a substrate on a main surface of the substrate held on a substrate holder and configured to form processing traces by moving the radiation point on dividing target lines of the substrate includes a processing unit configured to repeat, while switching the dividing target lines, moving the substrate holder in a first axis direction to move the irradiation point on the dividing target lines and configured to rotate the substrate holder around a third axis during the moving of the substrate holder to change a direction of the substrate held on the substrate holder by 180°.

FIG. 8